Polishing Slurry for Oxide layer CMP
ILD™

Fumed Silica Slurry for Oxide layer Polishing

ILD™ Series

◻ Advantages

- Particle stability (Lower scratch)
- High mechanical polishing ability
- Dilutable
- High purity
- KOH/NH3 base

◻ Physical Property

Slurry	ILD3013	ILD3225
Chemical	NH3	KOH
Abrasive （wt%）	13.7	25.7
pH	10.5	11.0
Particle size（nm）	85	85
Viscosity（cP）	1.8	3.7
Specific Gravity	1.08	1.17
Dilution	Ready to use	1:1 dilution

※ ILD™ is the trademark of NITTA DuPont Incorporated.
※ The values such as a physical properties indicated, show the standard value. The product specifications are not guaranteed.